

SPECIFICATION AMENDMENTS

At page 9 and continuing onto page 10, please amend Paragraph [0035] as follows:

[0035] FIGS. 6-8 are cross sections of SPC 100 in various stages of operation. FIG. 6 shows SPC 100 open with wafer 126 in an elevated position. Wafer 126 is inserted onto lift pin assembly 130, which is in the up position. In FIG. 7, lift pin assembly 130 has lowered wafer 126 onto proximity pins 133 on lower hot plate 132. Upper hot plate 124 is in an up position as are flow channel plate 112 and cover plate 110 of manifold 111. One or both of hot (chill) plates 124 and 134 132 may be active in this stage in order to heat or cool wafer 126. In addition, the gas may be flowing or may be turned off. Note the gap between the upper hot plate 124 and wafer 126.